

Call for Papers

iMAPS New England – 42nd Symposium & Expo

**The Largest Regional Symposium Dedicated to
Microelectronics and Packaging**



The New England Chapter

May 5, 2015

**Holiday Inn – Boxborough Woods Conference Center
Boxborough, Massachusetts**

- RF Microwave Materials and Processes
- Copper Wirebonding
- Surface Mount Technology
- Thermal Management
- Military and Defense Electronics
- Advanced Packaging with 3D and TSV
- Medical Devices
- High Temp Electronics
- Automotive & Consumer Applications
- Near Hermetic Packaging
- MEMS Sensors and Nano Technology
- Printed Electronics
- Optoelectronics

**Symposium Technical Co-Chairs
Tom Green, TJ Green Associates
Dmitry Marchenko, Microsemi**

Please e-mail your 250 word abstract to:
dmitry.marchenko@live.com

Deadline for Submission – December 31, 2014

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